

# Material Specification

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## PROJECT

Design name	: TEA1936x USB PD 45W Mobile Charging Adapter.		
Board-ID	: TEA1936xDB1521	PCB number	: 0000-000-4155-R1-00
Reference	: Patrick van den Hurk	Date	: 02-08-2017
Size single board	: 55.00 x 46.00 mm.	Size panel board	: 130.00 x 250.00 mm.
Size tolerance	: +0.10 -0.20 mm.	Composition	: 2x5, See Panel Drawing
Total layer(s)	: 2	Board thickness ( +/- 10%)	: <b>0.80 mm.</b>
Basic material	: <b>FR4</b>	Board finish	: ENIG
Cu thickness outer layer, finished	: <b>70 µm.</b>	Cu thickness inner layer	: -- µm.
SMD technologie	: Yes, both sides	Powerplanes	: No
Used via type(s)	: Through		
Pasta mask	: Yes, both sides	Peel-off mask	: No
Silkscreen	: Yes, both sides	Silkscreen colour	: White
Solder resist	: Yes, both sides	Solder resist colour	: Green

## PLOTTER INFORMATION

Units	: Millimeters
Gerber type	: RS274X
Data type	: Absolute X/Y-positive
Output code	: ASCII
Resolution	: 1/10000 mm.

## NC DRILL PARAMETERS

Units	: Imperial
Machine	: Excellon
Data format	: 3.5
Output code	: ASCII
Resolution	: 1/10000 inch

## NON PLATED THROUGH HOLES

Hole size tolerance, $\leq 0.2$ mm.	: +0.05 -0.05 mm.
$\geq 0.3$ mm.	: +0.1 -0.1mm.
Position tolerance	: +0.1 -0.1mm.

## PLATED THROUGH HOLES

Hole size tolerance, $\leq 0.2$ mm.	: +0.05 -0.05 mm.
$\geq 0.3$ mm.	: +0.1 -0.1mm.
Position tolerance	: +0.1 -0.1mm.

## MILL BOARD OUTLINES

The position from the boardoutline and boardcutouts represent the exact centerline to complete the dimensions. The milltool has to be positioned near the centerline with a offset half the diameter from the tool.

## SCORE BOARD OUTLINES

The position from the boardoutline represent the exact centerline to complete the dimensions. The score tool has to be positioned at the centerline.

## BOARD PROPERTIES

Min. isolation outer layer	: <b>200 µm.</b>	Min. isolation inner layer	: --- µm.
Min. track width outer layer	: <b>200 µm.</b>	Min. track width inner layer	: --- µm.
Min. hole diameter	: <b>0.2 mm.</b>		

## REMARKS

Manufacturer code allowed.

**NXP Logo** has to be **filled**.

Milling Through copper allowed.

Singel board has to be panalized, the number of times see panel drawing.

Panel has breakaway edges (10.00mm).

Panel has scoring grooves, both directions.

Add text: 9999-000-41551 and has to be done only in the breakaway edge.

Create a top and bottom paste file from the panel. Send this back to customer.

**Single boards on the left side kolom of the panel has to be rotaded 180 degrees.**

# Material Specification

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## FILES INCLUDED

Top Paste Mask	: 0000-000-4155-R1-00_SPT.gbx
Top Silkscreen	: 0000-000-4155-R1-00_SST.gbx
Top Solder Resist	: 0000-000-4155-R1-00_SMT.gbx
Top Signal Layer (L1)	: 0000-000-4155-R1-00_TOP.gbx
Bottom Signal Layer (L2)	: 0000-000-4155-R1-00_BOT.gbx
Bottom Solder Resist	: 0000-000-4155-R1-00_SMB.gbx
Bottom Silkscreen	: 0000-000-4155-R1-00_SSB.gbx
Bottom Paste Mask	: 0000-000-4155-R1-00_SPB.gbx
<del>Milling Non Plated</del>	<del>: 0000-000-4155-R1-00_MNP.gbx</del>
<del>Milling Plated</del>	<del>: 0000-000-4155-R1-00_MPL.gbx</del>
NC Drill	: 0000-000-4155-R1-00-1-2.drl
<b>NC Route (slotted holes)</b>	<b>: 0000-000-4155-R1-00.rou</b>
Mechanical Dimensions	: 0000-000-4155-R1-00_DRD.gbx/.pdf
Panel Drawing	: 0000-000-4155-R1-00_PNL.gbx/.pdf
This File	: 0000-000-4155-R1-00_MSP.pdf